Product Summary

BV_{DSS}	$R_{DS(on)}$ Max	I_D Max T_A = +25°C
100V	32mΩ @ V_{GS} = 10V	5A
	49mΩ @ V_{GS} = 4.5V	4A

Features and Benefits

- High Conversion Efficiency
- Low $R_{DS(on)}$—Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- 100% Unclamped Inductive Switching (UIS) Test in Production – Ensures More Reliable and Robust End Application
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/**

Description and Applications

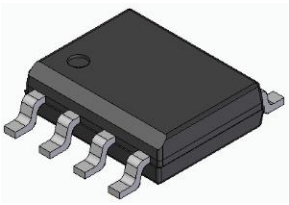
This MOSFET is designed to minimize the on-state resistance ($R_{DS(on)}$) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- High Frequency Switching
- Synchronous Rectification
- DC-DC Converters

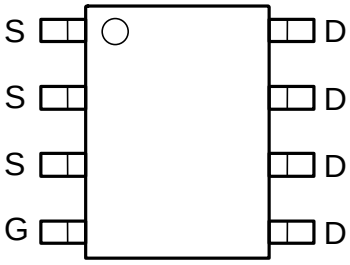
Mechanical Data

- Package: SO-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Finish—Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.074 grams (Approximate)

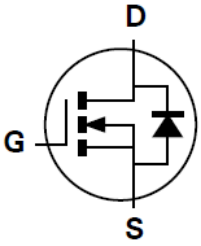
SO-8



Top View



Top View
Pin Configuration



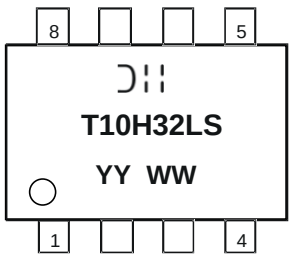
Equivalent Circuit

Ordering Information (Note 4)

Part Number	Package	Packing	
		Qty.	Carrier
DMT10H032LSS-13	SO-8	2500	Tape & Reel

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



⊃╎╎ = Manufacturer's Marking
T10H32LS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 21 = 2021)
WW = Week (01 to 53)

Maximum Ratings (@ T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	100	V
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current (Note 6) V_{GS} = 10V	T_A = +25°C T_A = +70°C	I_D	5 4	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I_{DM}	42	A
Maximum Continuous Body Diode Forward Current (Note 6)		I_S	25	A
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)		I_{SM}	42	A
Avalanche Current, L = 0.3mH		I_{AS}	13	A
Avalanche Energy, L = 0.3mH		E_{AS}	25.3	mJ

Thermal Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_D	1.3	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\Theta JA}$	100	°C/W
Total Power Dissipation (Note 6)	P_D	1.9	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\Theta JA}$	60	°C/W
Thermal Resistance, Junction to Case (Note 6)	$R_{\Theta JC}$	11	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	100	—	—	V	V_{GS} = 0V, I_D = 1mA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 80V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	1.3	—	2.5	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(on)}$	—	23	32	mΩ	V_{GS} = 10V, I_D = 10A
		—	34	49		V_{GS} = 4.5V, I_D = 6A
Diode Forward Voltage	V_{SD}	—	0.8	1.0	V	V_{GS} = 0V, I_S = 6A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	683	—	pF	V_{DS} = 50V, V_{GS} = 0V, f = 1MHz
Output Capacitance	C_{oss}	—	165	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	6.9	—	pF	
Gate Resistance	R_g	—	1.2	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = 4.5V)	Q_g	—	6.3	—	nC	V_{DS} = 50V, I_D = 6A
Total Gate Charge (V_{GS} = 10V)	Q_g	—	11.9	—	nC	
Gate-Source Charge	Q_{gs}	—	2.0	—	nC	
Gate-Drain Charge	Q_{gd}	—	3.1	—	nC	
Turn-On Delay Time	$t_{D(on)}$	—	4.1	—	ns	V_{DS} = 50V, R_L = 5.85Ω, V_{GS} = 10V, R_{GEN} = 3Ω
Turn-On Rise Time	t_R	—	4.5	—	ns	
Turn-Off Delay Time	$t_{D(off)}$	—	12.5	—	ns	
Turn-Off Fall Time	t_F	—	9.3	—	ns	
Reverse Recovery Time	t_{RR}	—	31.5	—	ns	I_F = 6A, di/dt = 500A/µs
Reverse Recovery Charge	Q_{RR}	—	94.6	—	nC	

Notes:
5. Device mounted on FR-4 substrate PCB, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PCB, 2oz copper, with 1inch square copper plate.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

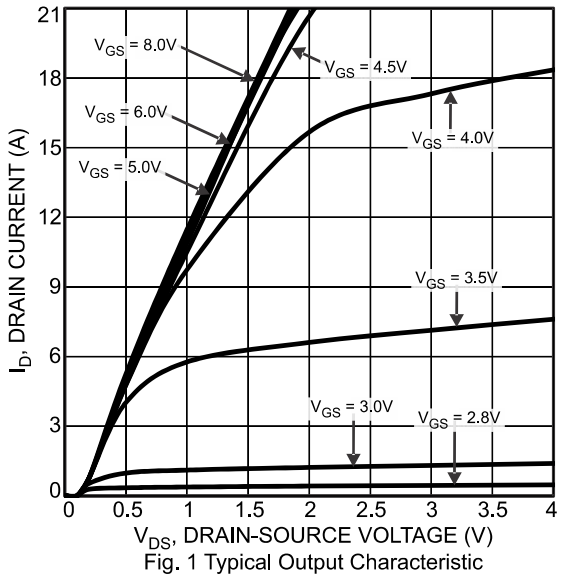


Fig. 1 Typical Output Characteristic

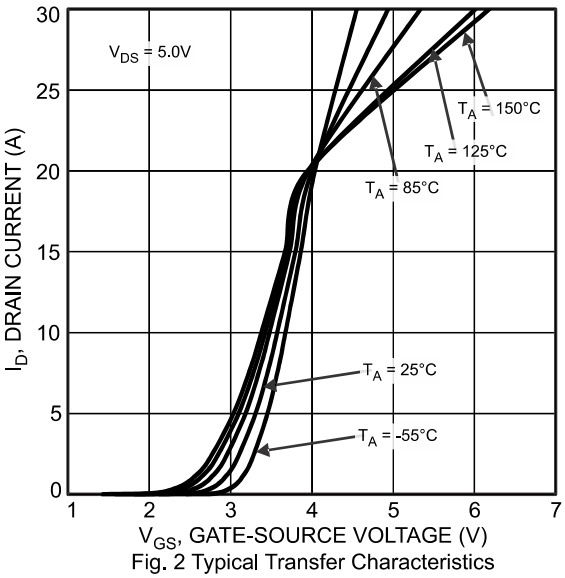


Fig. 2 Typical Transfer Characteristics

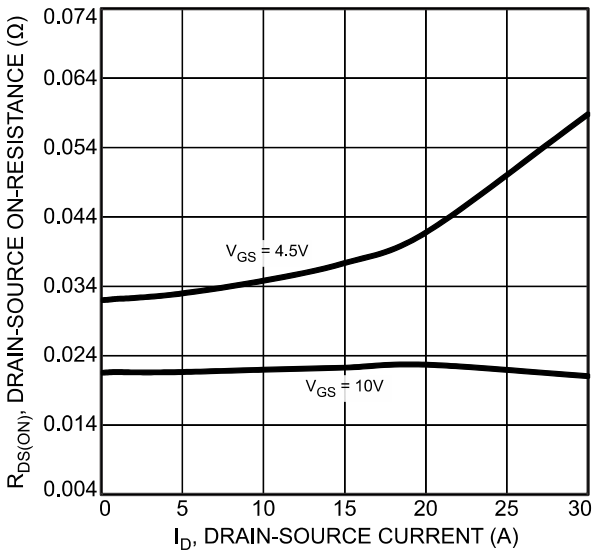


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

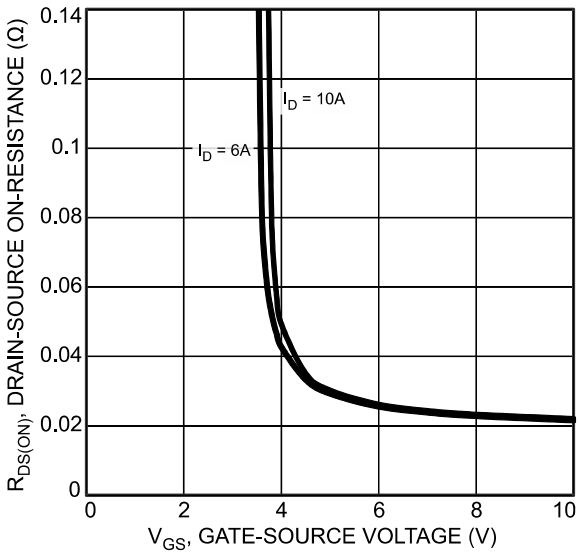


Fig. 4 Typical Drain-Source On-Resistance vs. Gate-Source Voltage

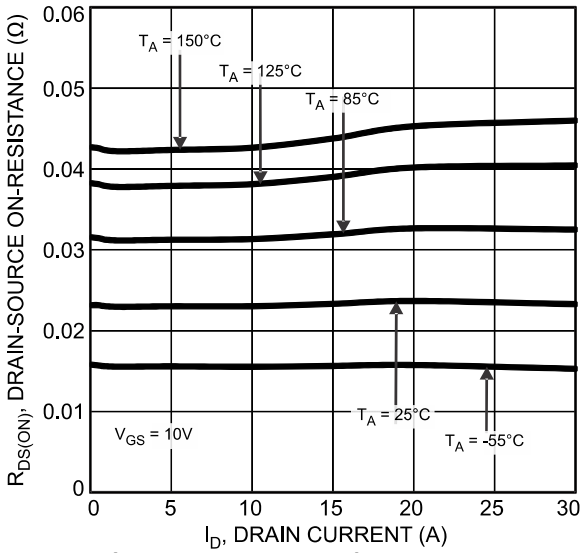


Fig. 5 Typical On-Resistance vs. Drain Current and Junction Temperature

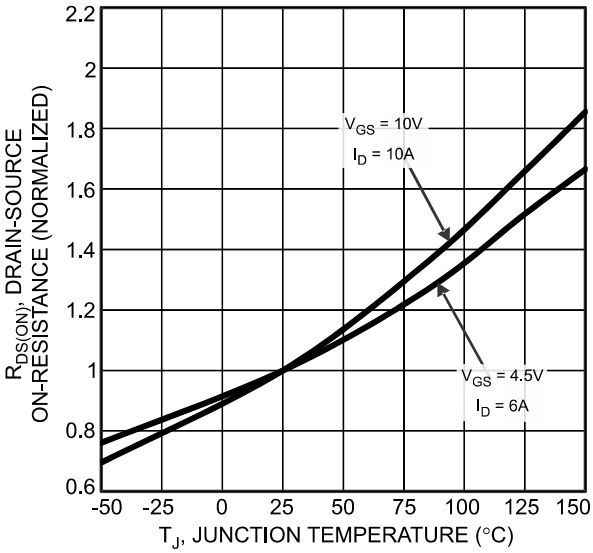


Fig. 6 On-Resistance Variation with Junction Temperature

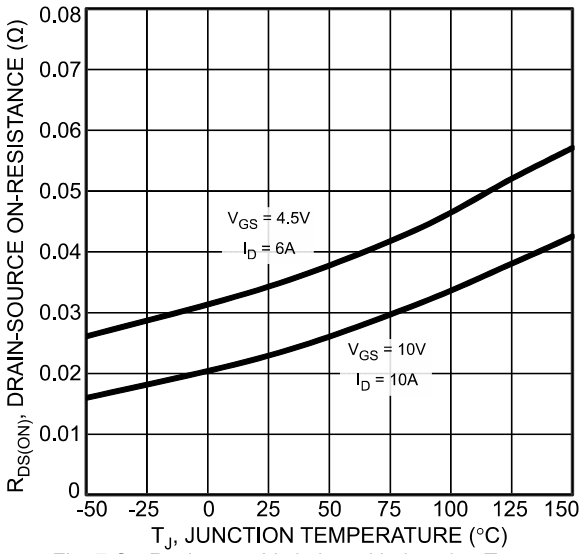


Fig. 7 On-Resistance Variation with Junction Temperature

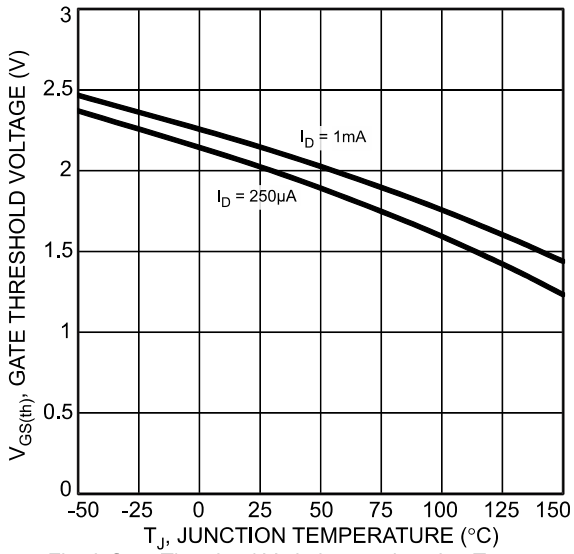


Fig. 8 Gate Threshold Variation vs. Junction Temperature

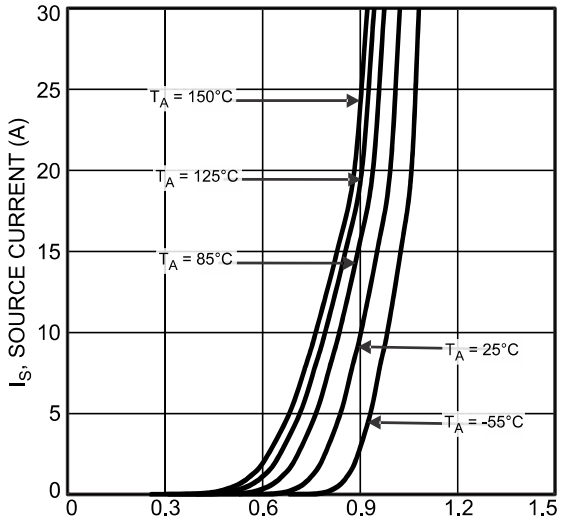


Fig. 9 Diode Forward Voltage vs. Current

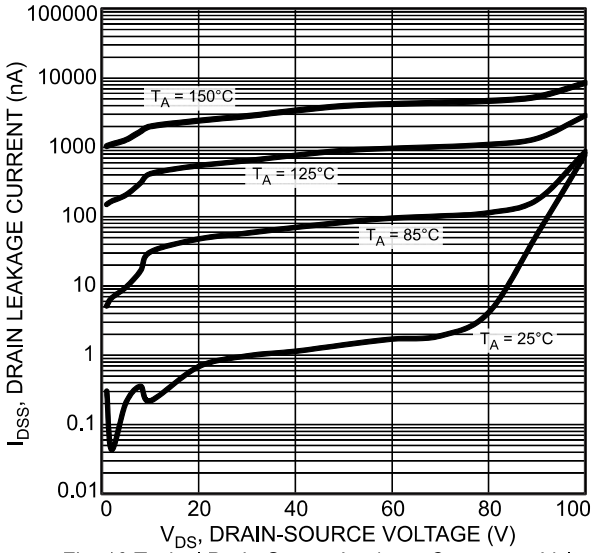


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage

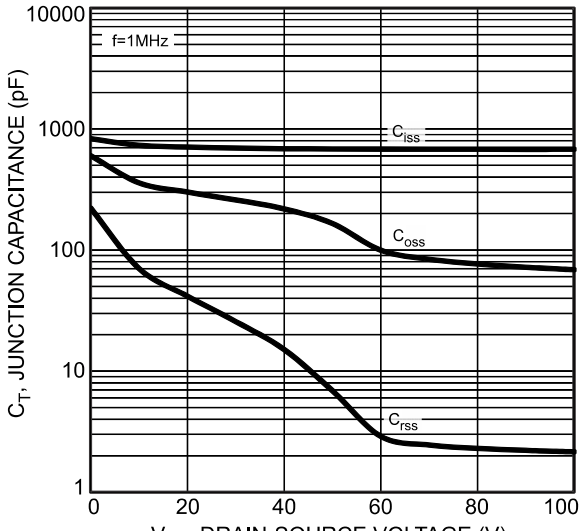


Fig. 10 Typical Junction Capacitance

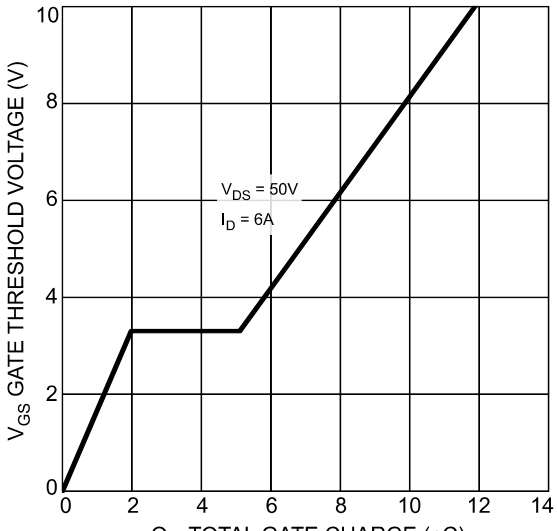


Fig. 12 Gate Charge

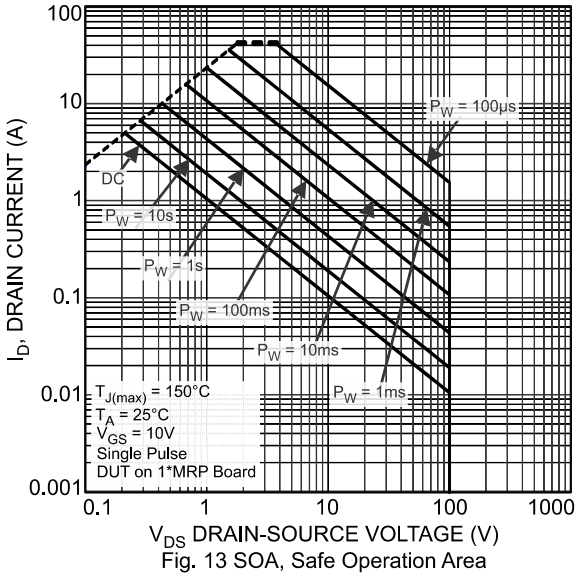


Fig. 13 SOA, Safe Operation Area

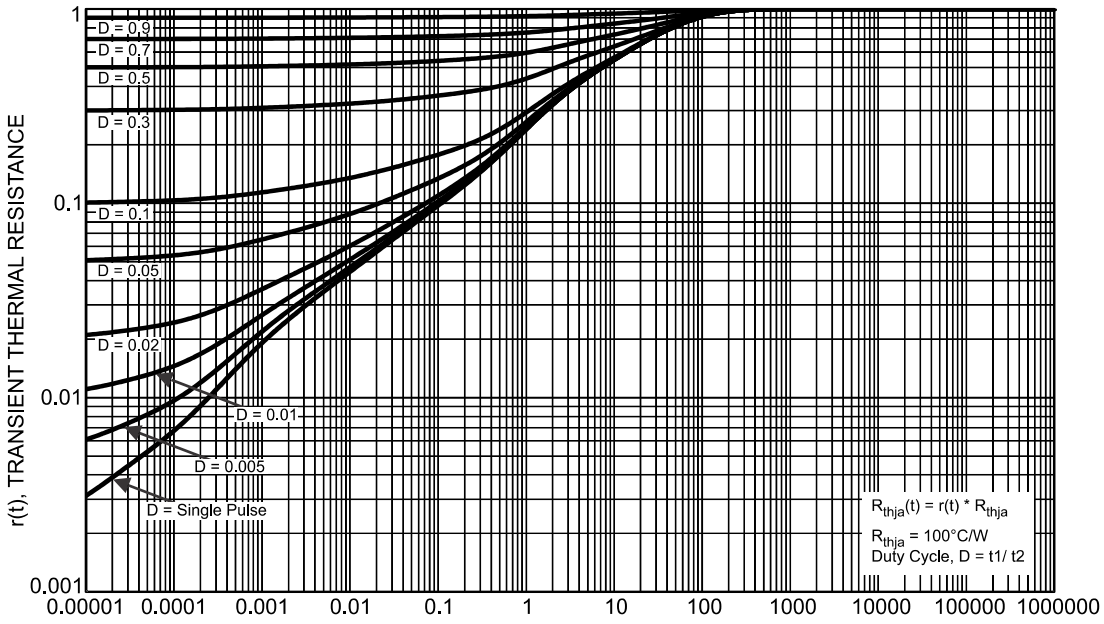
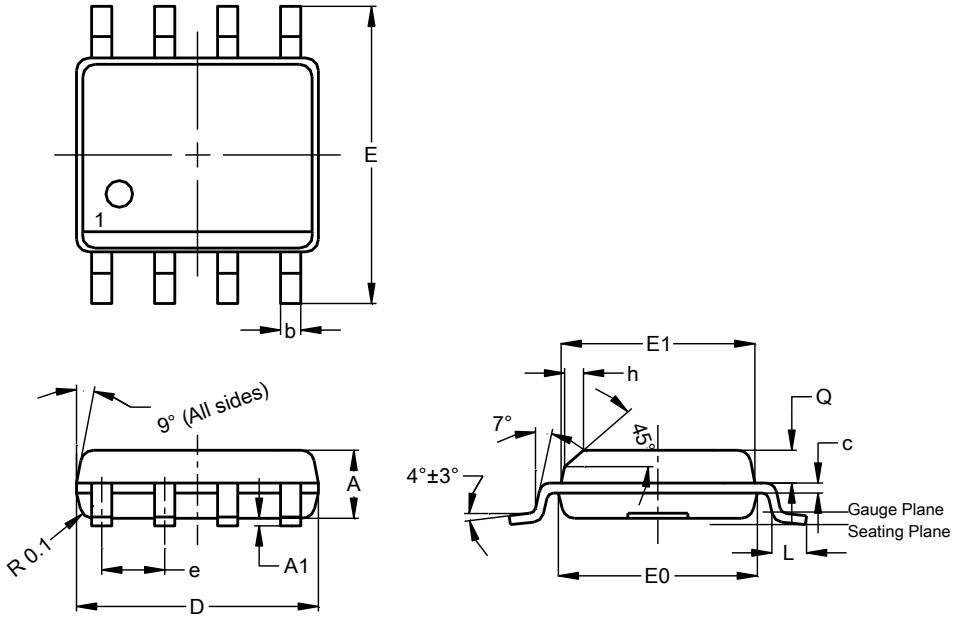


Fig. 14 Transient Thermal Resistance

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8

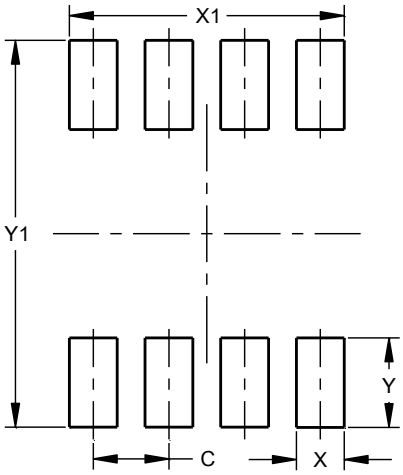


SO-8			
Dim	**Min**	**Max**	**Typ**
A	1.40	1.50	1.45
A1	0.10	0.20	0.15
b	0.30	0.50	0.40
c	0.15	0.25	0.20
D	4.85	4.95	4.90
E	5.90	6.10	6.00
E1	3.80	3.90	3.85
E0	3.85	3.95	3.90
e	--	--	1.27
h	--	--	0.35
L	0.62	0.82	0.72
Q	0.60	0.70	0.65
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



Dimensions	Value (in mm)
C	1.27
X	0.802
X1	4.612
Y	1.505
Y1	6.50

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